

CLAIMS

1. A thermosetting resin composition containing 100 parts by weight of a thermosetting resin and 0.1 to 100 parts by weight of an inorganic compound dispersed in said thermosetting resin, characterized in that the dispersion particle diameter of said inorganic compound is 2 μm or less and not less than 75% of the shape of an article molded before curing is maintained after the resin composition is cured.

2. The thermosetting resin composition according to claim 1, wherein said inorganic compound is an inorganic compound containing silicon and oxygen as a constituent element.

3. The thermosetting resin composition according to claim 1 or 2, wherein said inorganic compound is laminar silicate.

4. The thermosetting resin composition according to any one of claims 1 to 3, wherein said resin composition contains an epoxy resin as said thermosetting resin.

5. A material for substrates, characterized in that said material is composed by using the thermosetting resin composition according to any one of claims 1 to 4.

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6. A film for substrates, characterized in that said film is composed by using the thermosetting resin composition according to any one of claims 1 to 4.

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